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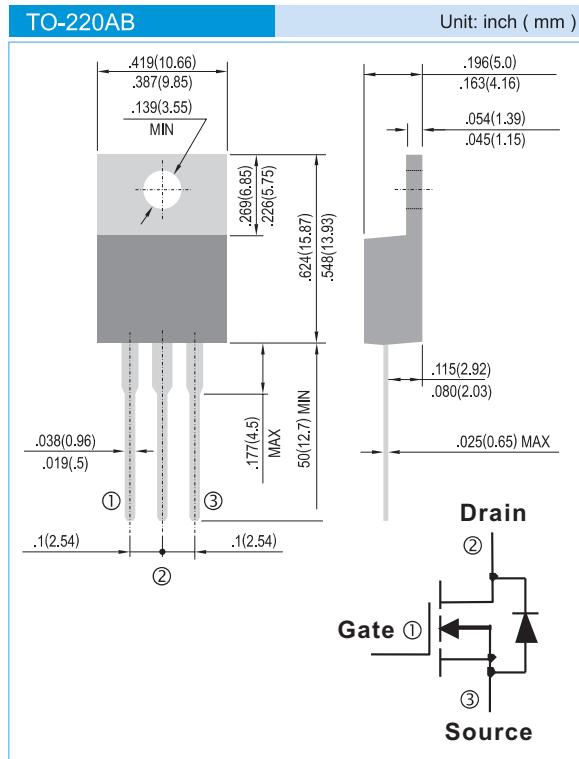
60V N-Channel Enhancement Mode MOSFET

FEATURES

- $R_{DS(ON)}$, $V_{GS} @ 10V, I_{DS} @ 30A = 14m\Omega$
- Advanced Trench Process Technology
- High Density Cell Design For Ultra Low On-Resistance
- Specially Designed for Converters and Power Motor Controls
- Fully Characterized Avalanche Voltage and Current
- In compliance with EU RoHS 2002/95/EC directives

MECHANICAL DATA

- Case: TO-220AB Molded Plastic
- Terminals : Solderable per MIL-STD-750, Method 2026
- Marking : P6000



Maximum RATINGS and Thermal Characteristics ($T_A=25^\circ C$ unless otherwise noted)

PARAMETER	Symbol	Limit	Units
Drain-Source Voltage	V_{DS}	60	V
Gate-Source Voltage	V_{GS}	± 20	V
Continuous Drain Current	I_D	60	A
Pulsed Drain Current ¹⁾	I_{DM}	210	A
Maximum Power Dissipation	P_D	90 53.5	W
Operating Junction and Storage Temperature Range	T_J, T_{STG}	-55 to +150	$^\circ C$
Avalanche Energy with Single Pulse $I_{AS}=37A$, $VDD=30V$, $L=0.3mH$	E_{AS}	410	mJ
Junction-to-Case Thermal Resistance	$R_{\theta JC}$	1.4	$^\circ C/W$
Junction-to Ambient Thermal Resistance(PCB mounted) ²⁾	$R_{\theta JA}$	62	$^\circ C/W$

Note: 1. Maximum DC current limited by the package

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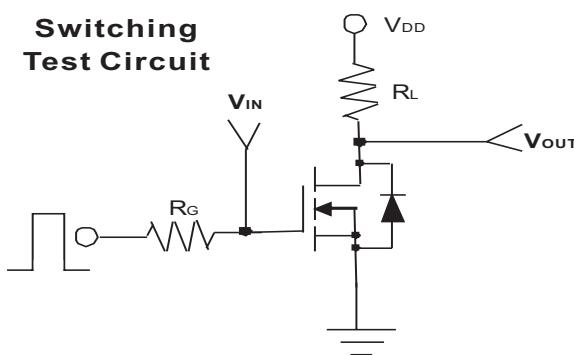


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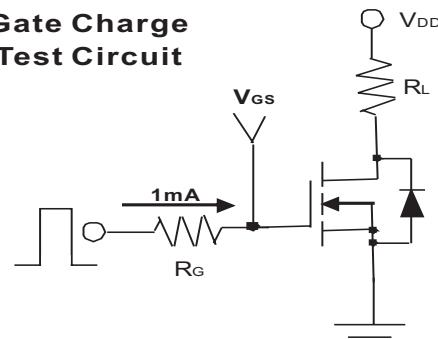
ELECTRICAL CHARACTERISTICS ($T_A=25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	Test Condition	Min.	Typ.	Max.	Units
Static						
Drain-Source Breakdown Voltage	BV_{DSS}	$V_{GS}=0\text{V}, I_D=250\mu\text{A}$	60	-	-	V
Gate Threshold Voltage	$V_{GS(\text{th})}$	$V_{DS}=V_{GS}, I_D=250\mu\text{A}$	1	-	3	V
Drain-Source On-State Resistance	$R_{DS(on)}$	$V_{GS}=10\text{V}, I_D=30\text{A}$	-	12	14	$\text{m}\Omega$
		$V_{GS}=10\text{V}, I_D=30\text{A}, T_c=125^\circ\text{C}$	-	-	26	
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS}=60\text{V}, V_{GS}=0\text{V}$	-	-	1	μA
		$V_{DS}=60\text{V}, V_{GS}=0\text{V}, T_c=125^\circ\text{C}$	-	-	10	
Gate Body Leakage	I_{GSS}	$V_{GS}=\pm 20\text{V}, V_{DS}=0\text{V}$	-	-	± 100	nA
Forward Transconductance	g_{fs}	$V_{DS}>I_{D(\text{ON})} \times R_{DS(\text{ON})\text{max}}, I_D=15\text{A}$	25	-	-	S
Dynamic						
Total Gate Charge	Q_g	$V_{DS}=30\text{V}, I_D=30\text{A}$ $V_{GS}=10\text{V}$	-	40	-	nC
Gate-Source Charge	Q_{gs}		-	3.8	-	
Gate-Drain Charge	Q_{gd}		-	12	-	
Turn-On Delay Time	$t_{d(on)}$	$V_{DD}=30\text{V}, R_L=15\Omega$ $I_D=2\text{A}, V_{GEN}=10\text{V}$ $R_G=2.5\Omega$	-	14.6	20	ns
Turn-On Rise Time	t_r		-	14.2	18	
Turn-Off Delay Time	$t_{d(off)}$		-	40	60	
Turn-Off Fall Time	t_f		-	7.3	9.5	
Input Capacitance	C_{iss}	$V_{DS}=25\text{V}, V_{GS}=0\text{V}$ $f=1.0\text{MHz}$	-	1480	-	pF
Output Capacitance	C_{oss}		-	190	-	
Reverse Transfer Capacitance	C_{rss}		-	135	-	
Source-Drain Diode						
Max. Diode Forward Current	I_s	-	-	-	60	A
Diode Forward Voltage	V_{SD}	$I_s=30\text{A}, V_{GS}=0\text{V}$	-	0.94	1.2	V

Switching Test Circuit



Gate Charge Test Circuit





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Typical Characteristics Curves ($T_g=25^\circ\text{C}$, unless otherwise noted)

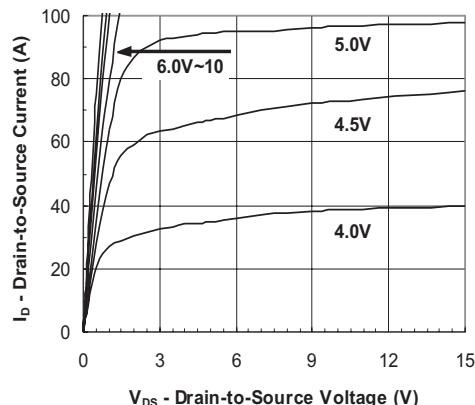


FIG.1- Output Characteristic

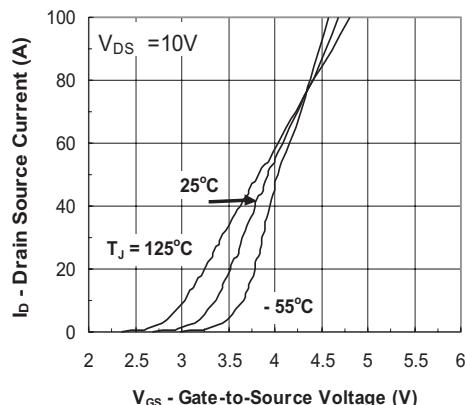


FIG.2- Transfer Characteristic

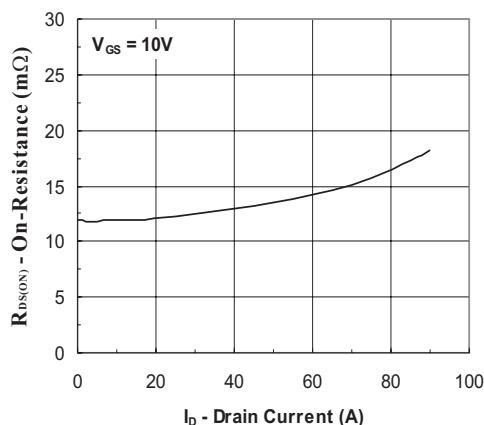


FIG.3- On Resistance vs Drain Current

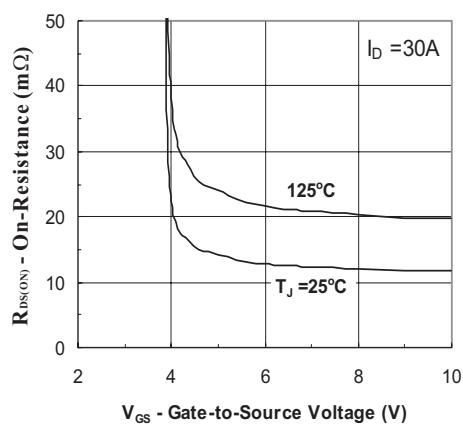


FIG.4- On Resistance vs Gate to Source Voltage

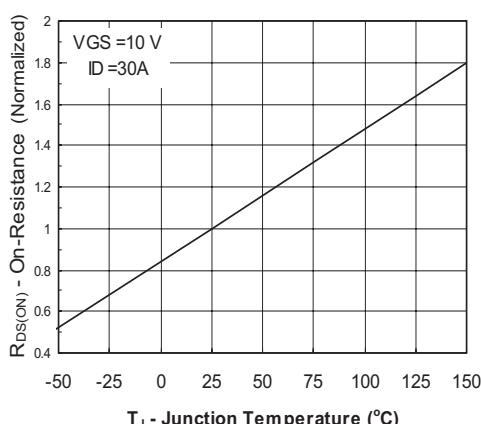


FIG.5- On Resistance vs Junction Temperature

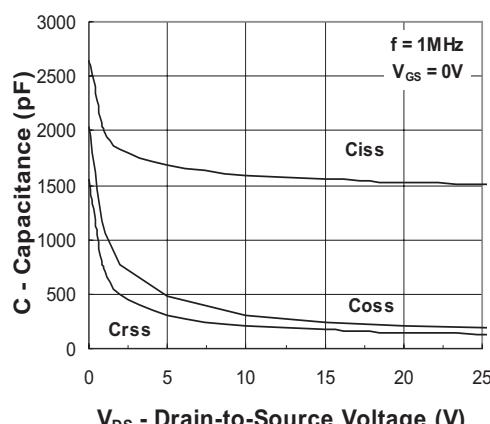


FIG.6 - Capacitance



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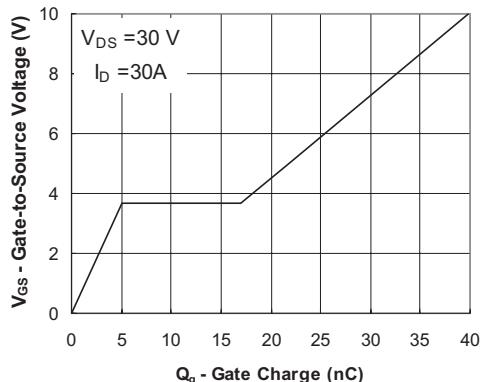


Fig.7 - Gate Charge

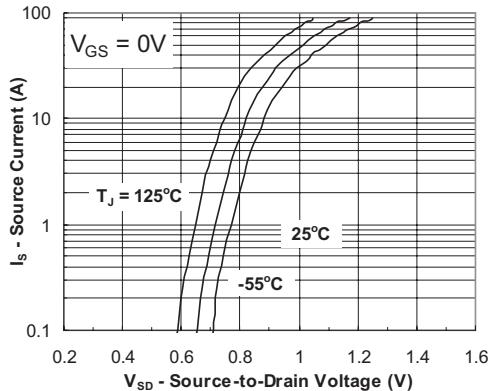


Fig.10 - Source-Drain Diode Forward Voltage

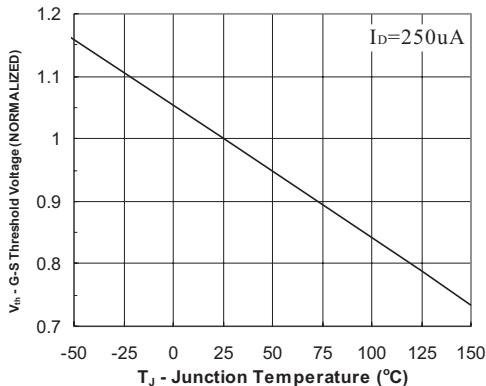


Fig.8 - Threshold Voltage vs Junction Temperature

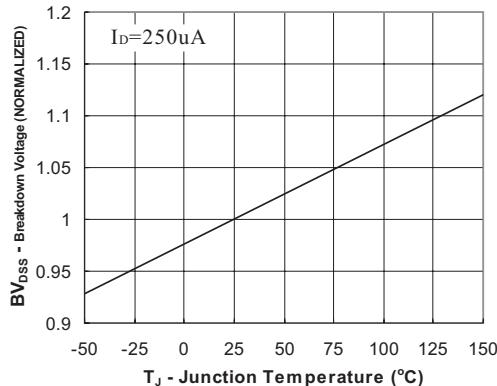


Fig.9 - Breakdown Voltage vs Junction Temperature

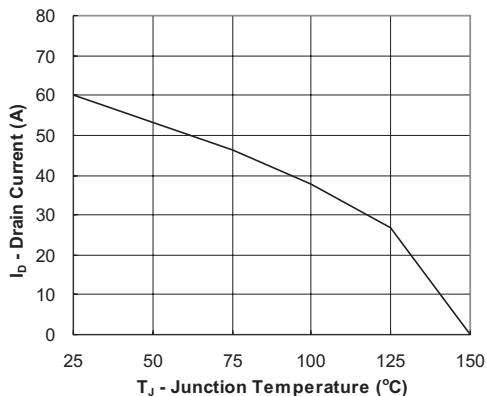


Fig.11 - Maximum Drain Current vs Junction Temperature

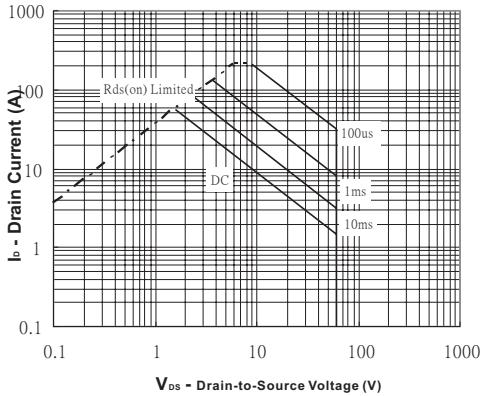


Fig.12 - Safe Operation Area